Japan TC Chapter of
Assembly & Packaging Global Technical Committee
Meeting Summary and Minutes

Japan Standards Fall 2015 Meetings
Friday, October 16, 2015, 1:30 p.m. – 3:30 p.m. [JST]
SEMI Japan office, Tokyo, Japan

Next Committee Meeting
Friday, February 5, 2016, 1:30 p.m. – 3:00 p.m. [JST]
Japan Standards Winter 2016 Meetings, Tokyo, Japan

Committee Announcements (optional)
None

Table 1 Meeting Attendees
*italics indicates virtual participants
Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuriya (iNEMI)
SEMI Staff: Chie Yanagisawa (SEMI Japan)
Attendee: 14 + SEMI: 1

<table>
<thead>
<tr>
<th>Company</th>
<th>Last</th>
<th>First</th>
<th>Company</th>
<th>Last</th>
<th>First</th>
</tr>
</thead>
<tbody>
<tr>
<td>AIST</td>
<td>Shimamoto</td>
<td>Haruo</td>
<td>iNEMI</td>
<td>Tsuriya</td>
<td>Masahiro</td>
</tr>
<tr>
<td>AiT</td>
<td>Kato</td>
<td>Kazunori</td>
<td>Micron Memory Japan</td>
<td>Sonobe</td>
<td>Kaoru</td>
</tr>
<tr>
<td>DISCO</td>
<td>Masuchi</td>
<td>Sumio</td>
<td>Nidec-Read Corporation</td>
<td>Miyazaki</td>
<td>Yoko</td>
</tr>
<tr>
<td>Fasford Technology</td>
<td>Mochizuki</td>
<td>Masayuki</td>
<td>Samusung</td>
<td>Kajinami</td>
<td>Masato</td>
</tr>
<tr>
<td>Fasford Technology</td>
<td>Tsuchiya</td>
<td>Kunihiro</td>
<td>Shin-Etsu Polymer</td>
<td>Shinozuka</td>
<td>Nobuhiro</td>
</tr>
<tr>
<td>Hitachi High-Technologies</td>
<td>Yoshino</td>
<td>Eiji</td>
<td>Toray Engineering</td>
<td>Asahi</td>
<td>Noboru</td>
</tr>
<tr>
<td>Hitachi Kokusai Electric</td>
<td>Matsuda</td>
<td>Mitsuhiro</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>HST Vision</td>
<td>Sasaki</td>
<td>Kunihiko</td>
<td>SEMI Japan</td>
<td>Yanagisawa</td>
<td>Chie</td>
</tr>
</tbody>
</table>

* alphabetical order by company name

Table 2 Leadership Changes

<table>
<thead>
<tr>
<th>Group</th>
<th>Previous Leader</th>
<th>New Leader</th>
</tr>
</thead>
<tbody>
<tr>
<td>None</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Table 3 Ballot Results (or move to Section 4, Ballot Review)
Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.
Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

<table>
<thead>
<tr>
<th>Document #</th>
<th>Document Title</th>
<th>Committee Action</th>
</tr>
</thead>
<tbody>
<tr>
<td>5835</td>
<td>New Standard: SPECIFICATION FOR ADHESIVE TRAY USED FOR THIN CHIP HANDLING</td>
<td>Passed with editorial changes</td>
</tr>
</tbody>
</table>

Table 4 Authorized Ballots (or move to Section 7, New Business)

<table>
<thead>
<tr>
<th>#</th>
<th>When SC/TF/WG</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td>None</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Table 5 Authorized Activities (or move to Section 7, New Business)

<table>
<thead>
<tr>
<th>#</th>
<th>Type</th>
<th>SC/TF/WG</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td>None</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Table 6 New Action Items (or move to Section 8, Action Item Review)

<table>
<thead>
<tr>
<th>Item #</th>
<th>Assigned to</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td>None</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Table 7 Previous Meeting Actions Items (or move to Section 8, Action item Review)

<table>
<thead>
<tr>
<th>Item #</th>
<th>Assigned to</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td>20150511-1</td>
<td>SEMI Staff</td>
<td>To send a message to Yutaka Koma that his stepping down from the co-chair was approved at Assembly &amp; Packaging Japan TC Chapter meeting on May 11, 2015. =&gt;CLOSESD</td>
</tr>
</tbody>
</table>

1 Welcome, Reminders, and Introductions

Masahiro Tsuriya (iNEMI) called the meeting to order at 1:30 p.m. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

Motion: To approve the minutes of the previous meeting as written.
By / 2nd: Kazunori Kato (AiT) / Sumio Masuchi (DISCO)
Discussion: None
Vote: 7 in favor and 0 opposed. 4 Abstain. Motion passed.

3 Liaison Reports

3.1 3DS-IC Japan TC Chapter

Masahiro Tsuriya reported that the formation of the 3DS-IC Japan TC Chapter was approved by JRSC in August 2015, the kick-off TC Chapter meeting was held on September 9, and the second TC Chapter meeting would be held on October 16, after this meeting.

3.2 3DS-IC North America TC Chapter

Chie Yanagisawa (SEMI Japan) reported for the 3DS-IC North America TC Chapter as attached.

Attachment: 01, NA 3DS-IC report September 2015

3.3 3DS-IC Taiwan TC Chapter

Chie Yanagisawa (SEMI Japan) reported for the 3DS-IC Taiwan TC Chapter as attached.

Attachment: 02, Taiwan 3DS-IC Liaison Report Oct 2015

Masahiro Tsuriya stated that the 3DS-IC TC Chapter liaison reports would not be presented after the next meeting of the Assembly & Packaging Japan TC Chapter, because they would be presented at the 3DS-IC Japan TC Chapter meetings.

3.4 SEMI Staff Report

Chie Yanagisawa (SEMI Japan) gave the SEMI Staff Report. Of note:

- Global SEMI Events
• Global Standards Meetings Schedule
  o NA Fall Meetings
  o SEMICON Japan
• Ballot Critical Dates
• Publication Update
• A&R Ballot Review
• New Requirements/Process Reminders for TC Chapter Meetings
• Contact Information

Attachment: 03, SEMI Staff Report 2015.10.15

4 Ballot Review

4.1 Document #5835, New Standard: SPECIFICATION FOR ADHESIVE TRAY USED FOR THIN CHIP HANDLING
This ballot was reviewed and passed with editorial changes at this meeting. The details of ballot reviews are found in the attachment.

Attachment: 04, 5835_LetterBallotReviewSheet

5 Subcommittee & Task Force Reports

5.1 GCS
No report was made at this TC Chapter meeting.

5.2 Electromagnetic Characterization Study Group
No report was made at this TC Chapter meeting.

5.3 Japan 450mm Assembly & Test Die Preparation Task Force
No report was made at this TC Chapter meeting.

5.4 Thin Chip Handling Task Force
Ballot #5835 “New Standard: SPECIFICATION FOR ADHESIVE TRAY USED FOR THIN CHIP HANDLING” was reviewed and passed with editorial changes at this meeting.

5.5 Packaging 5 Year Review Task Force
The details would be reported at the Old Business section of this meeting later.

5.6 3D-IC Study Group
No report was made at this TC Chapter meeting.

5.7 Fiducial Mark Interoperability Task Force
Due to the time limitation, no report was made but the task force report is provided as the attachment.

Attachment: 05, 20150911FMI-TF-Report_r1

6 Old Business

6.1 5 Year Review Check
Kazunori Kato (AiT) addressed the committee on this topic. He mentioned that there were Assembly & Packaging documents that was planned for reapproval, however, some of them might be required for revision due to the
nonconforming titles (per Appendix 4 of SEMI Standards Procedure Manual) or due to lack of sections that should include depending on Standards types (per 3.2 of SEMI Standards Procedure Manual). So, the task force would discuss and would like to propose what to do for each document for 5 year review at the next TC Chapter meeting.

6.2 SNARF Project Period Check
There was no SNARF that three year passed since its initial approval.

7 New Business

7.1 Backend Issue from Information & Control (I&C) Japan TC Chapter
Mitsuhiro Matsuda (Hitachi Kokusai Electric) addressed the committee on this topic. He mentioned that the TC Chapter was resumed in Taiwan region this year and it seemed interested in Backend Automation so “Backend Factory Integration TF” was set up. The I&C Japan TC Chapter could hardly understand and collaborate with the activity of Backend Factory Integration TF due to only few Standards members in the I&C Japan TC Chapter involved in the backend. So, as a co-chair of the I&C Japan TC Chapter, he would like to ask for cooperation of this TC Chapter. The task force has not been kicked-off yet, but the I&C Japan TC Chapter could provide the inform to the Assembly & Packaging Japan TC Chapter whenever it recognize any activity of the TF.

8 Action Item Review

8.1 Open Action Items
Chie Yanagisawa (SEMI Japan) reviewed the open action items. The TC Chapter found there was nothing for the Open Action Items.

8.2 New Action Items
There was no new action item.

9 Next Meeting and Adjournment
The next meeting of the Assembly & Packaging Japan TC Chapter is scheduled for Friday, February 5, 2016, 1:30 p.m. – 3:00 p.m. at Japan Standards Winter Meetings at SEMI Japan office in Tokyo, Japan.
Table 8 Index of Available Attachments #1

<table>
<thead>
<tr>
<th>#</th>
<th>Title</th>
<th>#</th>
<th>Title</th>
</tr>
</thead>
<tbody>
<tr>
<td>01</td>
<td>NA 3DS-IC report September 2015</td>
<td>04</td>
<td>5835_LetterBallotReviewSheet</td>
</tr>
<tr>
<td>02</td>
<td>Taiwan 3DS-IC Liaison Report Oct 2015</td>
<td>05</td>
<td>20150911FMI-TF-Report_r1</td>
</tr>
<tr>
<td>03</td>
<td>SEMI Staff Report 2015.10.15</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.